

Chaoqi Zhang

List of Publications by Year in descending order

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citing authors

#	ARTICLE	IF	CITATIONS
1	Highly Elastic Gold Passivated Mechanically Flexible Interconnects. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2013, 3, 1632-1639.	2.5	25
2	Self-Aligned Silicon Interposer Tiles and Silicon Bridges Using Positive Self-Alignment Structures and Rematable Mechanically Flexible Interconnects. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2014, 4, 1760-1768.	2.5	15
3	Thermal Isolation Using Air Gap and Mechanically Flexible Interconnects for Heterogeneous 3-D ICs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 31-39.	2.5	13
4	Mechanically flexible interconnects (MFIs) with highly scalable pitch. Journal of Micromechanics and Microengineering, 2014, 24, 055024.	2.6	10
5	Mechanically Flexible Interconnects With Contact Tip for Rematable Heterogeneous System Integration. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1587-1594.	2.5	8
6	A Self-Aligning Flip-Chip Assembly Method Using Sacrificial Positive Self-Alignment Structures. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 471-477.	2.5	6
7	Mechanically flexible interconnects with highly scalable pitch and large stand-off height for silicon interposer tile and bridge interconnection. , 2014, , .		5
8	Gold passivated mechanically flexible interconnects (MFIs) with high elastic deformation. , 2012, , .		4
9	Interposer-to-interposer electrical and silicon photonic interconnection platform using silicon bridge. , 2014, , .		4
10	Au-NiW Mechanically Flexible Interconnects (MFIs) and TSV integration for 3D interconnects. , 2014, , .		3
11	A microfabricated electronic microplate platform for low-cost repeatable biosensing applications. , 2015, , .		3
12	Fabrication of and cell growth on "silicon membranes"™ with high density TSVs for bio-sensing applications. , 2015, , .		2
13	Revolutionary innovation in system interconnection: a new era for the IC. , 2011, , .		1